



## Material Content Data Sheet



Halogen-Free

Sales Product Name	IKB30N65EH5	Issued	24. February 2022
MA#	MA005708938		
Package	PG-TO263-3-2	Weight*	1562.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.381	0.09	0.09	884	884
chip_2	inorganic material	silicon	7440-21-3	1.761	0.11	0.11	1127	1127
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.46	19.49	194630	194883
wire	non noble metal	aluminium	7429-90-5	11.698	0.75	0.75	7489	7489
encapsulation	inorganic material	zinc oxide	1314-13-2	6.808	0.44		4358	
	miscellaneous	miscellaneous	-	27.231	1.74		17432	
	plastics	epoxy resin	-	102.114	6.54		65371	
	inorganic material	silicon dioxide	60676-86-0	544.610	34.86	43.58	348647	435808
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6182	6182
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.076			48	
	noble metal	silver	7440-22-4	0.095	0.01		61	
	non noble metal	lead	7439-92-1	3.613	0.23	0.24	2313	2422
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.06	35.11	350602	351058
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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